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penetration holes disposed in said substrate so as to form a matrix of one of aligned rows and aligned columns of penetration holes;

a circuit wiring disposed on both sides of said substrate; and

a chip component having a height almost the same as a depth of each of said penetration holes, said chip component being disposed in one of said penetration holes for electrically coupling said circuit wiring disposed on both sides of said substrate.

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4. (Amended) A module component according to claim 1, further comprising a fixing member for filling up a gap between said chip component and said one of said penetration holes.

5. (Amended) A module component according to claim 1, wherein at least one of the penetration holes is tapered.

6. (Amended) A module component according to claim 1, wherein support means is formed at said one of said penetration holes for supporting said chip component.

7. (Amended) A module component according to claim 1, further comprising an auxiliary substrate disposed over at least one side of the substrate.

8. (Amended) A module component comprising:

a substrate made of resin having a penetration hole;

a circuit wiring disposed on both sides of said substrate; and
first and second auxiliary substrates disposed such that said substrate is
disposed between said first and second auxiliary substrates, and
a chip component disposed in the penetration hole, said chip component having
a specified height being greater than the depth of the penetration hole and not
projecting from said first and second auxiliary substrates, said chip component
electrically coupling said circuit wiring disposed on both sides of said substrate,
wherein the penetration hole is formed at a position according to a matrix.

134 10. (Amended) A module component comprising:
a substrate made of resin having a penetration hole;
a circuit wiring disposed on both sides of said substrate;
a chip component having a height almost same as a depth of said penetration
hole and put in the penetration hole for electrically coupling said circuit wiring disposed
on both sides of said substrate;
an auxiliary substrate disposed over said substrate;
an IC chip mounted on said auxiliary substrate; and
a capacitor put in said penetration hole immediately beneath said IC chip to be
coupled directly with said IC chip,
wherein the penetration hole is formed at a position according to a matrix.

11. (Amended) A module component according to claim 1, further comprising a
ground layer disposed beneath said substrate, said ground layer being coupled with

said circuit wiring disposed on a lower side of said substrate.

12. (Amended) A module component comprising:

a substrate made of resin having a penetration hole;

a circuit wiring disposed on both sides of said substrate; and

a chip component having a height almost the same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate;

an auxiliary substrate disposed over said substrate;

an IC chip mounted on said auxiliary substrate; and

a ground layer disposed beneath said substrate,

wherein the penetration hole is formed at a position according to a matrix;

wherein a chip component having a specific value is accommodated to compose a desired circuit; and

wherein said IC chip is coupled directly with said ground layer.

Please add new claims 31-35 as follows:

31. (New) A module component comprising:

a substrate made of resin having a penetration hole;

a circuit wiring disposed on both sides of said substrate;

a chip component having a height almost same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate; and

wherein the penetration hole is formed at a position according to a matrix,
wherein a chip component having a specific value is accommodated to compose
a desired circuit, and

wherein the penetration hole is tapered.

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32. (New) A module component comprising:

a substrate made of resin having a penetration hole;

a circuit wiring disposed on both sides of said substrate;

a chip component having a height almost same as a depth of said penetration
hole and put in the penetration hole for electrically coupling said circuit wiring disposed
on both sides of said substrate; and

a ground layer disposed beneath said substrate, said ground layer being coupled
with said circuit wiring disposed on a lower side of said substrate,

wherein the penetration hole is formed at a position according to a matrix, and

wherein a chip component having a specific value is accommodated to compose
a desired circuit.

33. (New) A module component comprising:

a substrate made of resin having a penetration hole;

a circuit wiring disposed on both sides of said substrate;

a chip component having a height almost same as a depth of said penetration
hole and put in the penetration hole for electrically coupling said circuit wiring disposed
on both sides of said substrate;

an auxiliary substrate disposed over said substrate; and
a ground layer disposed beneath said auxiliary substrate, said ground layer
being coupled with said circuit wiring disposed on a lower side of said substrate.

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34. (New) A module component comprising:
a substrate made of resin having a penetration hole;
a circuit wiring disposed on both sides of said substrate;
a chip component having a height almost same as a depth of said penetration
hole and put in the penetration hole for electrically coupling said circuit wiring disposed
on both sides of said substrate;
an auxiliary substrate disposed over said substrate;
an IC chip mounted on said auxiliary substrate; and
a ground layer disposed beneath said auxiliary substrate,
wherein the penetration hole is formed at a position according to a matrix, and
wherein said IC chip is coupled directly with said ground layer.

35. (New) A module component according to claim 1, further comprising a
dummy component disposed in another penetration hole of said penetration holes, said
dummy component having a size almost the same as said chip component and
functioning as an insulator.